



FINAL PRODUCT/PROCESS CHANGE NOTIFICATION

Generic Copy

01-Sep-2005

SUBJECT: ON Semiconductor Final Product/Process Change Notification #15014

TITLE: Released as 15011 - Seremban Assembly/Test Site Addition for Analog High Frequency 3x3 16-Lead QFN Package

EFFECTIVE DATE: 01-Nov-2005

AFFECTED CHANGE CATEGORY(S): ON Semiconductor Assembly and Test Site

AFFECTED PRODUCT DIVISION(S): Analog Power Products

ADDITIONAL RELIABILITY DATA: Available

Contact your local ON Semiconductor Sales Office or Matt Kas <fft7yg@onsemi.com>

SAMPLES: Contact your local ON Semiconductor Sales Office

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:

Contact your local ON Semiconductor Sales Office or John Veto <rtrtd61@onsemi.com>

NOTIFICATION TYPE:

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 60 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact your local ON Semiconductor Sales Office.

DESCRIPTION AND PURPOSE:

****Originally released as 15011****

This is an FPCN to IPCN 13296 available at www.onsemi.com

ON Semiconductor is pleased to announce the qualification of the ON Semiconductor Seremban facility located in Seremban, Malaysia to assemble and test the listed Analog High Frequency products in the 16 Lead 3x3 QFN package. Currently, the listed devices are manufactured and tested by ASAT (Hong Kong and China). There will be no changes in device functionality. Reliability will continue to meet or exceed ON Semiconductor's highest standards.

**Final Product/Process Change Notification #15011****RELIABILITY DATA SUMMARY:**

The following reliability results are for Seremban (SBN) 3X3 QFN Package, NCP1422 device.

Reliability Test Results:

Test	Conditions	Results
HTOL	TA=125°C, 504 hrs	0/231
HTB	TA=150°C, 1008 hrs	0/231
Preconditioning(PC)	MSL 1, 260° C	0/693
PC -Temp Cycle	-65/+150°C for 1000 cycles	0/231
PC -Autoclave	121°C/100%RH/15psig for 96hrs	0/231
PC -HAST	131°C/80%RH for 96 hrs	0/231
Solder Heat	260°C 10 seconds	0/90
Physical Dim. Case Outline		0/30
Wire Pull Per Factory		0/30, Cpk >1.33
Ball Shear Per Factory		0/30, Cpk >1.33
Die Shear Per Factory		0/30, Cpk >1.33
Solderability	Per Jedec	0/135

ELECTRICAL CHARACTERISTIC SUMMARY:

All product performance meets current datasheet specifications. Data is available upon request.

CHANGED PART IDENTIFICATION:

Assembly/Test location code in date code marking will change from "9" to "R".



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AFFECTED DEVICE LIST

PART

- NB4L16MMN
- NB4L16MMNR2
- NB4L16MMNG
- NB4L16MMNR2G
- NB4N527SMN
- NB4N527SMNR2
- NB4N527SMNG
- NB4N527SMNR2G
- NB6L239MN
- NB6L239MNR2
- NB6L239MNG
- NB6L239MNR2G
- NB6N239SMN
- NB6N239SMNR2
- NB6N239SMNG
- NB6N239SMNR2G
- NB7L11MMN
- NB7L11MMNR2
- NB7L11MMNG
- NB7L11MMNR2G
- NB7L14MMN
- NB7L14MMNR2
- NB7L14MMNG
- NB7L14MMNR2G
- NB7L216MN
- NB7L216MNR2
- NB7L216MNG
- NB7L216MNR2G
- NB7L32MMNG
- NB7L32MMNR2G
- NB7L86MMN
- NB7L86MMNR2
- NB7L86MMNG
- NB7L86MMNR2G
- NBSG11MN
- NBSG11MNR2
- NBSG11MNG
- NBSG11MNR2G
- NBSG14MN
- NBSG14MNR2
- NBSG14MNG
- NBSG14MNR2G
- NBSG16MMN
- NBSG16MMNR2
- NBSG16MMNG
- NBSG16MMNR2G



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NBSG16MN
NBSG16MNR2
NBSG16MNG
NBSG16MNR2G
NBSG16RMN
NBSG16RMNR2
NBSG16VSMN
NBSG16VSMNR2
NBSG16VSMNG
NBSG16VSMNR2G
NBSG53AMN
NBSG53AMNR2
NBSG53AMNG
NBSG53AMNR2G
NBSG72AMN
NBSG72AMNR2
NBSG72AMNG
NBSG72AMNR2G
NBSG86AMN
NBSG86AMNR2
NBSG86AMNG
NBSG86AMNR2G